ABSTRACT

VACUUM MOLDING APPARATUS

A molding apparatus is provided for molding a leadframe, the molding apparatus comprising a mold having a leadframe-receiving area on its surface that is configured to receive and clamp the leadframe in the leadframe-receiving area. At least one molding cavity and a plurality of vacuum suction holes formed adjacent to the molding cavity are located within the leadframe-receiving area. The vacuum suction holes are operative to evacuate air from the mold surface, especially the molding cavity, through air vents connecting the vacuum suction holes to the molding cavity.

(FIG. 2)